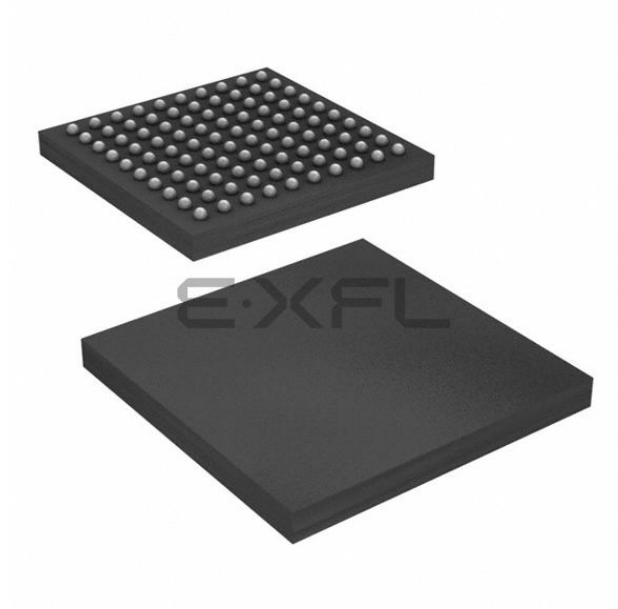

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	e200z4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, Ethernet, FlexRay, I²C, LINbus, SPI
Peripherals	DMA, I²S, POR, WDT
Number of I/O	-
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	256K x 8
Voltage - Supply (Vcc/Vdd)	3.15V ~ 5.5V
Data Converters	A/D 36x10b, 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LFBGA
Supplier Device Package	100-MAPBGA (11x11)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/spc5745bk1cmh2r

1 Block diagram

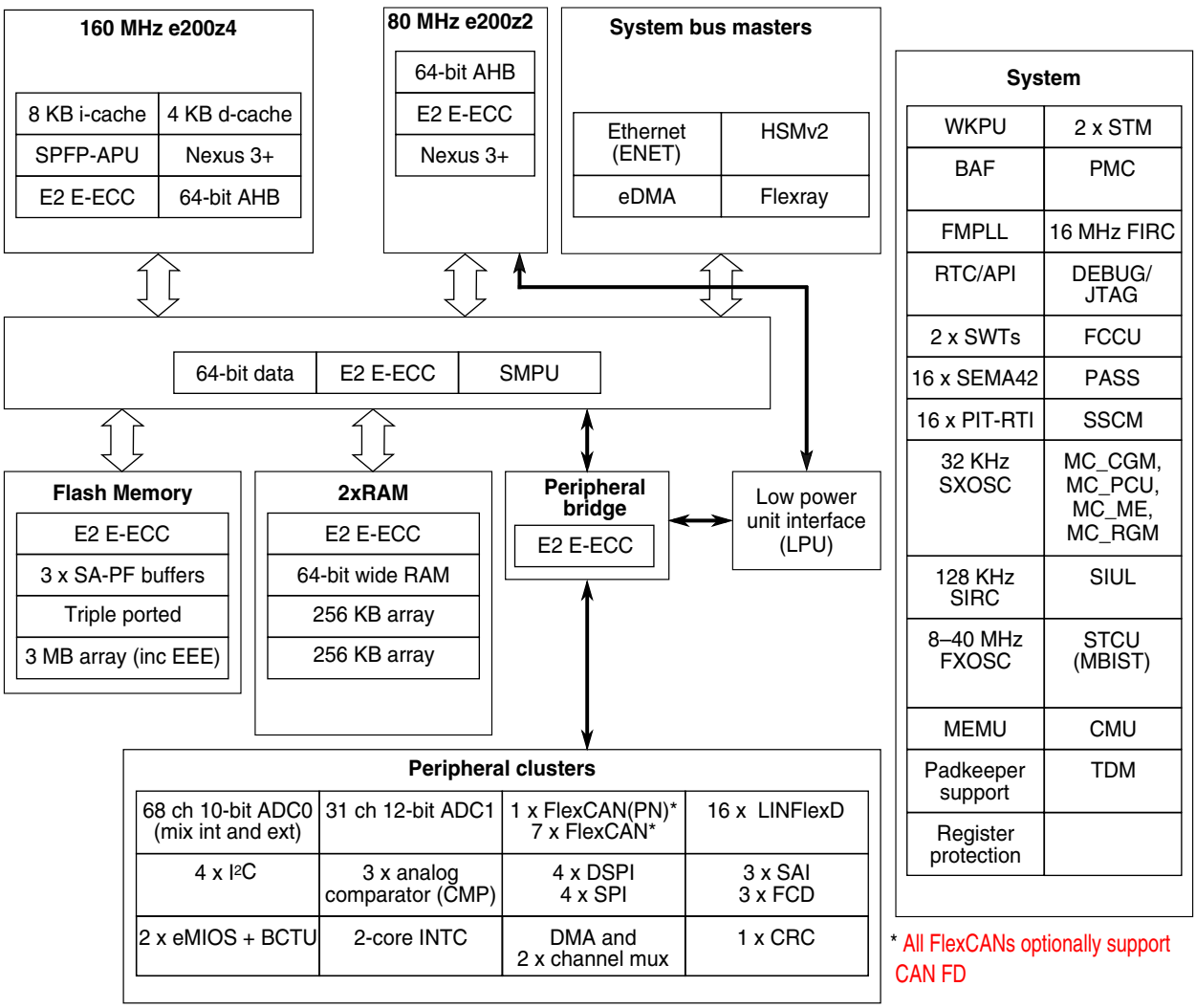

Figure 1. MPC5746C block diagram

2 Family comparison

The following table provides a summary of the different members of the MPC5746C family and their proposed features. This information is intended to provide an understanding of the range of functionality offered by this family. For full details of all of the family derivatives please contact your marketing representative.

Table 1. MPC5746C Family Comparison[1] (continued)

Feature	MPC5745B	MPC5744B	MPC5746B	MPC5744C	MPC5745C	MPC5746C
I^2C	4	4	4	4		
SAI/I^2S	3	3	3	3		
FXOSC	8 - 40 MHz					
SXOSC	32 KHz					
FIRC	16 MHz					
SIRC	128 KHz					
FMPLL	1					
Low Power Unit (LPU)	Yes					
FlexRay 2.1 (dual channel)	Yes, 128 MB	Yes, 128 MB	Yes, 128 MB	Yes, 128 MB		
Ethernet (RMII, MII + 1588, Muti queue AVB support)	1	1	1	1		
CRC	1					
MEMU	2					
STCU2	1					
HSM-v2 (security)	Optional					
Censorship	Yes					
FCCU	1					
Safety level	Specific functions ASIL-B certifiable					
User MBIST	Yes					
I/O Retention in Standby	Yes					
GPIO[6]	Up to 264 GPI and up to 246 GPIO					
Debug	JTAGC, cJTAG					
Nexus	Z4 N3+ (Only available on 324BGA (development only)) Z2 N3+ (Only available on 324BGA (development only))					
Packages	176 LQFP-EP 256 BGA 100 BGA	176 LQFP-EP 256 BGA 100 BGA	176 LQFP-EP 256 BGA 100 BGA	176 LQFP-EP 256 BGA 100 BGA	176 LQFP-EP 256 BGA 100 BGA	176 LQFP-EP 256 BGA, 324 BGA (development only) 100 BGA

1. Feature set dependent on selected peripheral multiplexing, table shows example. Peripheral availability is package dependent.
2. Based on 125°C ambient operating temperature and subject to full device characterization.
3. Contact NXP representative for part number
4. Additional SWT included when HSM option selected
5. See device datasheet and reference manual for information on to timer channel configuration and functions.
6. Estimated I/O count for largest proposed packages based on multiplexing with peripherals.

4. VDD_LV supply pins should never be grounded (through a small impedance). If these are not driven, they should only be left floating
5. VIN1_CMP_REF ≤ VDD_HV_A
6. This supply is shorted VDD_HV_A on lower packages.
7. T_J=150°C. Assumes T_A=125°C
    - Assumes maximum θJA of 2s2p board. See Thermal attributes

4.3 Voltage regulator electrical characteristics

The voltage regulator is composed of the following blocks:

- Choice of generating supply voltage for the core area.
    - Control of external NPN ballast transistor
    - Generating core supply using internal ballast transistor
    - Connecting an external 1.25 V (nominal) supply directly without the NPN ballast
- Internal generation of the 3.3 V flash supply when device connected in 5V applications
- External bypass of the 3.3 V flash regulator when device connected in 3.3V applications
- Low voltage detector - low threshold (LVD_IO_A_LO) for $V_{DD\_HV\_IO\_A\ supply}$
- Low voltage detector - high threshold (LVD_IO_A_Hi) for $V_{DD\_HV\_IO\_A\ supply}$
- Low voltage detector (LVD_FLASH) for 3.3 V flash supply (VDD_HV_FLA)
- Various low voltage detectors (LVD_LV_x)
- High voltage detector (HVD_LV_cold) for 1.2 V digital core supply (VDD_LV)
- Power on Reset (POR_LV) for 1.25 V digital core supply (VDD_LV)
- Power on Reset (POR_HV) for 3.3 V to 5 V supply (VDD_HV_A)

The following bipolar transistors[1] are supported, depending on the device performance requirements. As a minimum the following must be considered when determining the most appropriate solution to maintain the device under its maximum power dissipation capability: current, ambient temperature, mounting pad area, duty cycle and frequency for Idd, collector voltage, etc

1. BCP56, MCP68 and MJD31are guaranteed ballasts.

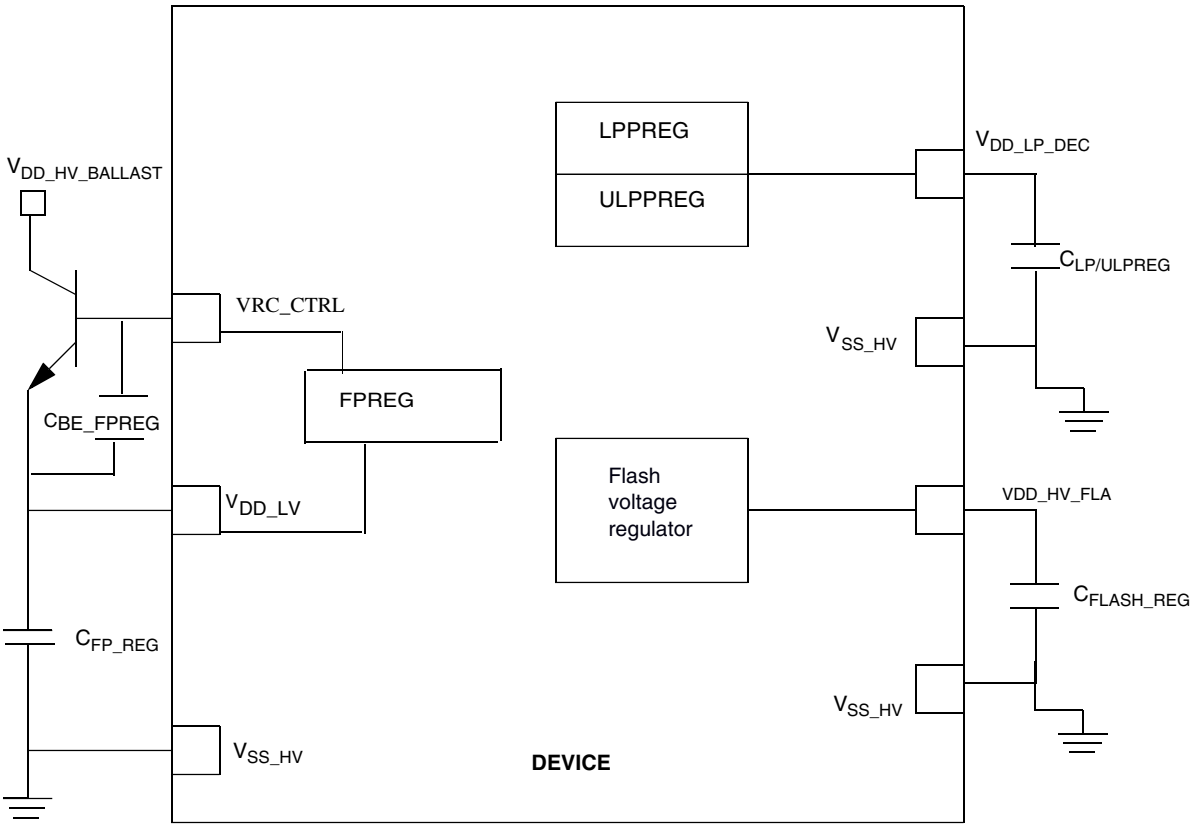

Figure 2. Voltage regulator capacitance connection

NOTE

On BGA, VSS_LV and VSS_HV have been joined on substrate and renamed as VSS.

Table 8. Voltage regulator electrical specifications

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{fp_reg}[1]	External decoupling / stability capacitor	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	1.32	2.2[2]	3	µF
	Combined ESR of external capacitor	—	0.001	—	0.03	Ohm
C_{lp/ulp_reg}	External decoupling / stability capacitor for internal low power regulators	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	0.8	1	1.4	µF
	Combined ESR of external capacitor	—	0.001	—	0.1	Ohm
C_{be_fpreg}[3]	Capacitor in parallel to base-emitter	BCP68 and BCP56		3.3		nF
		MJD31		4.7		

Table continues on the next page...

Table 8. Voltage regulator electrical specifications (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{flash_reg}[4]	External decoupling / stability capacitor for internal Flash regulators	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	1.32	2.2	3	µF
	Combined ESR of external capacitor	—	0.001	—	0.03	Ohm
$C_{HV\_VDD\_A}$	VDD_HV_A supply capacitor [5, 5]	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	1	—	—	µF
$C_{HV\_VDD\_B}$	VDD_HV_B supply capacitor[5]	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	1	—	—	µF
$C_{HV\_VDD\_C}$	VDD_HV_C supply capacitor[5]	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	1	—	—	µF
C_{HV_ADC0} C_{HV_ADC1}	HV ADC supply decoupling capacitances	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	1	—	—	µF
C_{HV_ADR}[6]	HV ADC SAR reference supply decoupling capacitances	Min, max values shall be granted with respect to tolerance, voltage, temperature, and aging variations.	0.47	—	—	µF
$V_{DD\_HV\_BALLAST}$[7]	FPREG Ballast collector supply voltage	When collector of NPN ballast is directly supplied by an on board supply source (not shared with VDD_HV_A supply pin) without any series resistance, that is, $R_{C\_BALLAST}$ less than 0.01 Ohm.	2.25	—	5.5	V
$R_{C\_BALLAST}$	Series resistor on collector of FPREG ballast	When VDD_HV_BALLAST is shorted to VDD_HV_A on the board	—	—	0.1	Ohm
t_{SU}	Start-up time with external ballastafter main supply (VDD_HV_A) stabilization	Cfp_reg = 3 µF	—	74	—	µs
t_{SU_int}	Start-up time with internal ballast after main supply (VDD_HV_A) stabilization	Cfp_reg = 3 µF	—	103	—	µs
t_{ramp}	Load current transient	Iload from 15% to 55% C_{fp_reg} = 3 µF		1.0		µs

1. Split capacitance on each pair VDD_LV pin should sum up to a total value of C_{fp_reg}
2. Typical values will vary over temperature, voltage, tolerance, drift, but total variation must not exceed minimum and maximum values.
3. Ceramic X7R or X5R type with capacitance-temperature characteristics +/-15% of -55 degC to +125degC is recommended. The tolerance +/-20% is acceptable.
4. It is required to minimize the board parasitic inductance from decoupling capacitor to VDD_HV_FLA pin and the routing inductance should be less than 1nH.

Table 12. STANDBY Current consumption characteristics (continued)

Symbol	Parameter	Conditions[1]	Min	Typ	Max	Unit
STANDBY2	STANDBY with 128K RAM	T_a = 25 °C	—	75	—	µA
		T_a = 85 °C	—	155	730	
		T_a = 105 °C	—	255	1350	
		T_a = 125 °C [2]	—	396	2600	
STANDBY3	STANDBY with 256K RAM	T_a = 25 °C	—	80	—	µA
		T_a = 85 °C	—	180	800	
		T_a = 105 °C	—	290	1425	
		T_a = 125 °C [2]	—	465	2900	
STANDBY3	FIRC ON	T_a = 25 °C	—	500	—	µA

1. The content of the Conditions column identifies the components that draw the specific current.
2. Assuming Ta=Tj, as the device is in static (fully clock gated) mode. Assumes maximum θJA of 2s2p board. SeeThermal attributes

4.6 Electrostatic discharge (ESD) characteristics

Electrostatic discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts × (n + 1) supply pin). This test conforms to the AEC-Q100-002/-003/-011 standard.

NOTE

A device will be defined as a failure if after exposure to ESD pulses the device no longer meets the device specification requirements. Complete DC parametric and functional testing shall be performed per applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

Table 13. ESD ratings

Symbol	Parameter	Conditions[1]	Class	Max value[2]	Unit
$V_{ESD(HBM)}$	Electrostatic discharge (Human Body Model)	T_A = 25 °C conforming to AEC-Q100-002	H1C	2000	V
$V_{ESD(CDM)}$	Electrostatic discharge (Charged Device Model)	T_A = 25 °C conforming to AEC-Q100-011	C3A	500 750 (corners)	V

1. All ESD testing is in conformity with CDF-AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits.
2. Data based on characterization results, not tested in production.

5.3 AC specifications @ 5 V Range

Table 16. Functional Pad AC Specifications @ 5 V Range

Symbol	Prop. Delay (ns)[1] L>H/H>L		Rise/Fall Edge (ns)		Drive Load (pF)	SIUL2_MSCRn[SRC 1:0]
	Min	Max	Min	Max		MSB,LSB
pad_sr_hv (output)		4.5/4.5		1.3/1.2	25	11
		6/6		2.5/2	50	
		13/13		9/9	200	
		5.25/5.25		3/2	25	10
		9/8		5/4	50	
		22/22		18/16	200	
		27/27		13/13	50	01[2, 2]
		40/40		24/24	200	
		40/40		24/24	50	00[2]
		65/65		40/40	200	
pad_i_hv/ pad_sr_hv (input)		1.5/1.5		0.5/0.5	0.5	NA

1. As measured from 50% of core side input to Voh/Vol of the output
2. Slew rate control modes

NOTE

The above specification is based on simulation data into an ideal lumped capacitor. Customer should use IBIS models for their specific board/loading conditions to simulate the expected signal integrity and edge rates of their system.

NOTE

The above specification is measured between 20% / 80%.

5.4 DC electrical specifications @ 5 V Range

Table 17. DC electrical specifications @ 5 V Range

Symbol	Parameter	Value		Unit
		Min	Max	
Vih (pad_i_hv)	pad_i_hv Input Buffer High Voltage	0.7*VDD_HV_x	VDD_HV_x + 0.3	V

Table continues on the next page...

Table 17. DC electrical specifications @ 5 V Range (continued)

Symbol	Parameter	Value		Unit
		Min	Max	
Vil (pad_i_hv)	pad_i_hv Input Buffer Low Voltage	VDD_HV_x - 0.3	0.45*VDD_HV_x	V
Vhys (pad_i_hv)	pad_i_hv Input Buffer Hysteresis	0.09*VDD_HV_x		V
Vih_hys	CMOS Input Buffer High Voltage (with hysteresis enabled)	0.65* VDD_HV_x	VDD_HV_x + 0.3	V
Vil_hys	CMOS Input Buffer Low Voltage (with hysteresis enabled)	VDD_HV_x - 0.3	0.35*VDD_HV_x	V
Vih	CMOS Input Buffer High Voltage (with hysteresis disabled)	0.55 * VDD_HV_x[1, 1]	VDD_HV_x[1] + 0.3	V
Vil	CMOS Input Buffer Low Voltage (with hysteresis disabled)	VDD_HV_x - 0.3	0.40 * VDD_HV_x[1]	V
Vhys	CMOS Input Buffer Hysteresis	0.09 * VDD_HV_x[1]		V
Pull_IIH (pad_i_hv)	Weak Pullup Current[2, 2] Low	23		µA
Pull_IIH (pad_i_hv)	Weak Pullup Current[3, 3] High		82	µA
Pull_IIL (pad_i_hv)	Weak Pulldown Current[3] Low	40		µA
Pull_IIL (pad_i_hv)	Weak Pulldown Current[2] High		130	µA
Pull_Ioh	Weak Pullup Current[4]	30	80	µA
Pull_Iol	Weak Pulldown Current[5]	30	80	µA
Iinact_d	Digital Pad Input Leakage Current (weak pull inactive)	-2.5	2.5	µA
Voh	Output High Voltage[6]	0.8 * VDD_HV_x[1]	—	V
Vol	Output Low Voltage[7] Output Low Voltage[8]	—	0.2*VDD_HV_x 0.1*VDD_HV_x	V
Ioh_f	Full drive Ioh[9, 9] (SIUL2_MSCRn.SRC[1:0] = 11)	18	70	mA
Iol_f	Full drive Iol[9] (SIUL2_MSCRn.SRC[1:0] = 11)	21	120	mA
Ioh_h	Half drive Ioh[9] (SIUL2_MSCRn.SRC[1:0] = 10)	9	35	mA
Iol_h	Half drive Iol[9] (SIUL2_MSCRn.SRC[1:0] = 10)	10.5	60	mA

1. VDD_HV_x = VDD_HV_A, VDD_HV_B, VDD_HV_C
2. Measured when pad=0.69*VDD_HV_x
3. Measured when pad=0.49*VDD_HV_x
4. Measured when pad = 0 V
5. Measured when pad = VDD_HV_x
6. Measured when pad is sourcing 2 mA
7. Measured when pad is sinking 2 mA
8. Measured when pad is sinking 1.5 mA
9. Ioh/Iol is derived from spice simulations. These values are NOT guaranteed by test.

5.5 Reset pad electrical characteristics

The device implements a dedicated bidirectional RESET pin.

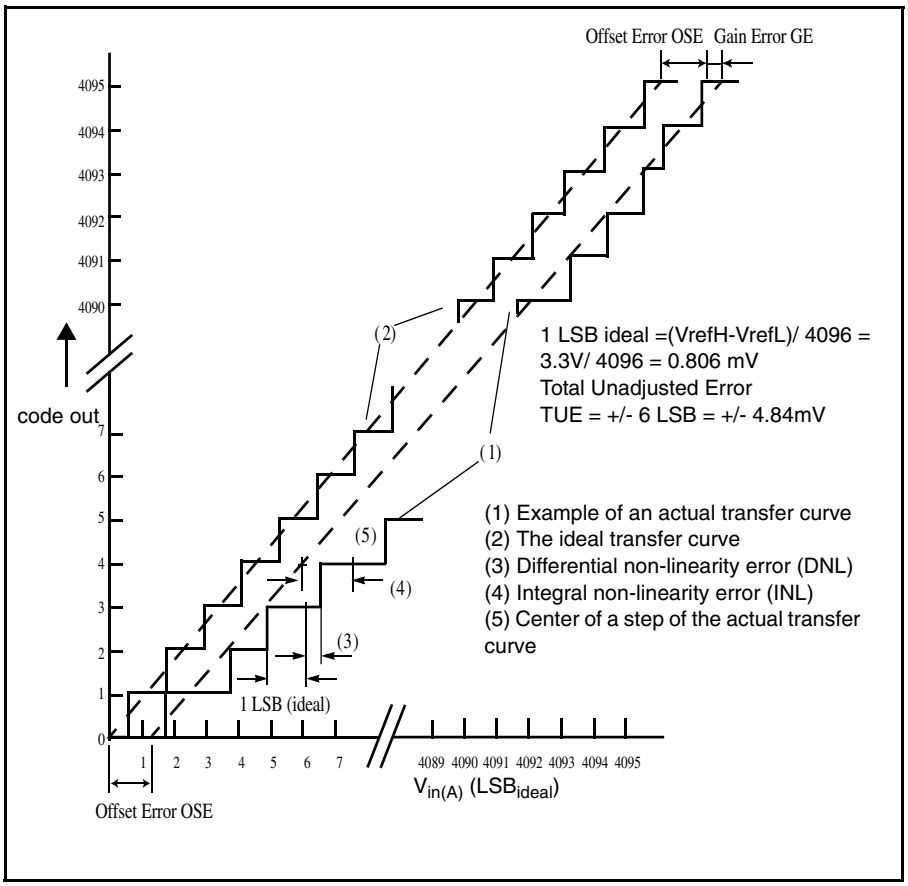

Figure 5. ADC characteristics and error definitions

6.2 Clocks and PLL interfaces modules

6.2.1 Main oscillator electrical characteristics

This device provides a driver for oscillator in pierce configuration with amplitude control. Controlling the amplitude allows a more sinusoidal oscillation, reducing in this way the EMI. Other benefits arises by reducing the power consumption. This Loop Controlled Pierce (LCP mode) requires good practices to reduce the stray capacitance of traces between crystal and MCU.

An operation in Full Swing Pierce (FSP mode), implemented by an inverter is also available in case of parasitic capacitances and cannot be reduced by using crystal with high equivalent series resistance. For this mode, a special care needs to be taken regarding the serial resistance used to avoid the crystal overdrive.

Other two modes called External (EXT Wave) and disable (OFF mode) are provided. For EXT Wave, the drive is disabled and an external source of clock within CMOS level based in analog oscillator supply can be used. When OFF, EXTAL is pulled down by 240 Kohms resistor and the feedback resistor remains active connecting XTAL through EXTAL by 1M resistor.

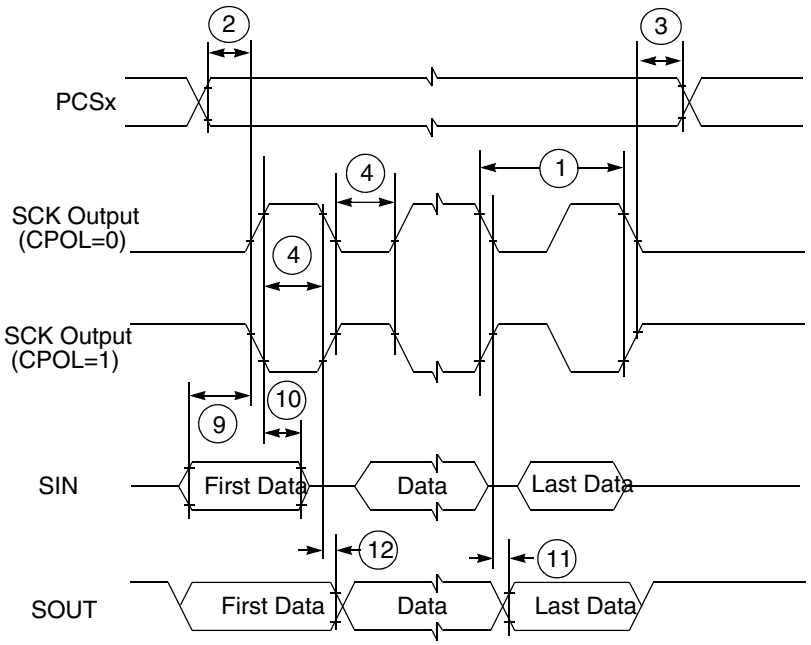

Figure 8. DSPI classic SPI timing — master, CPHA = 0

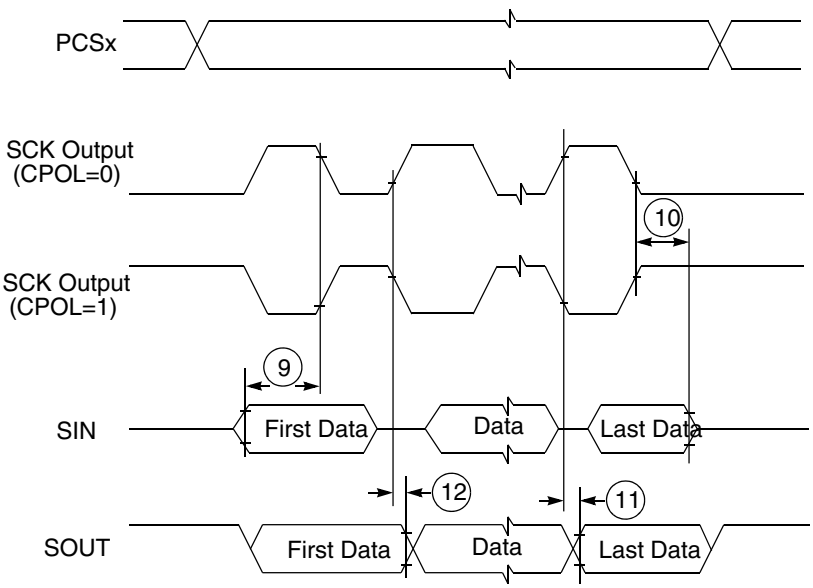

Figure 9. DSPI classic SPI timing — master, CPHA = 1

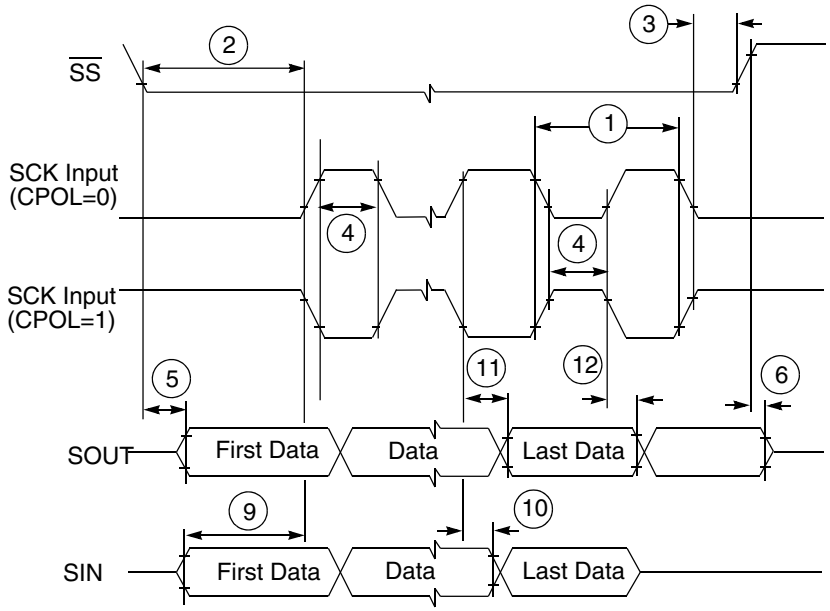

Figure 14. DSPI modified transfer format timing – slave, CPHA = 0

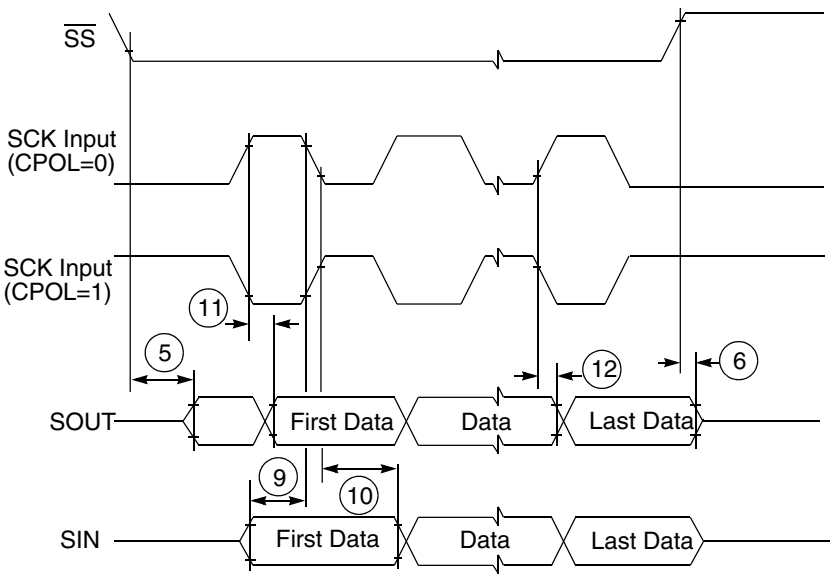

Figure 15. DSPI modified transfer format timing — slave, CPHA = 1

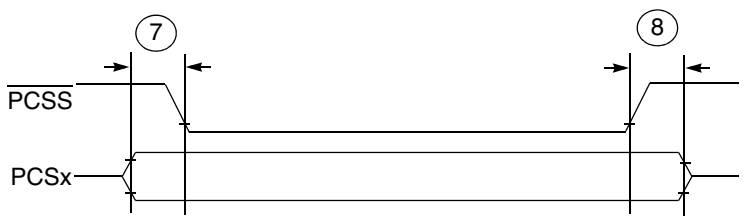

Figure 16. DSPI PCS strobe (PCSS) timing

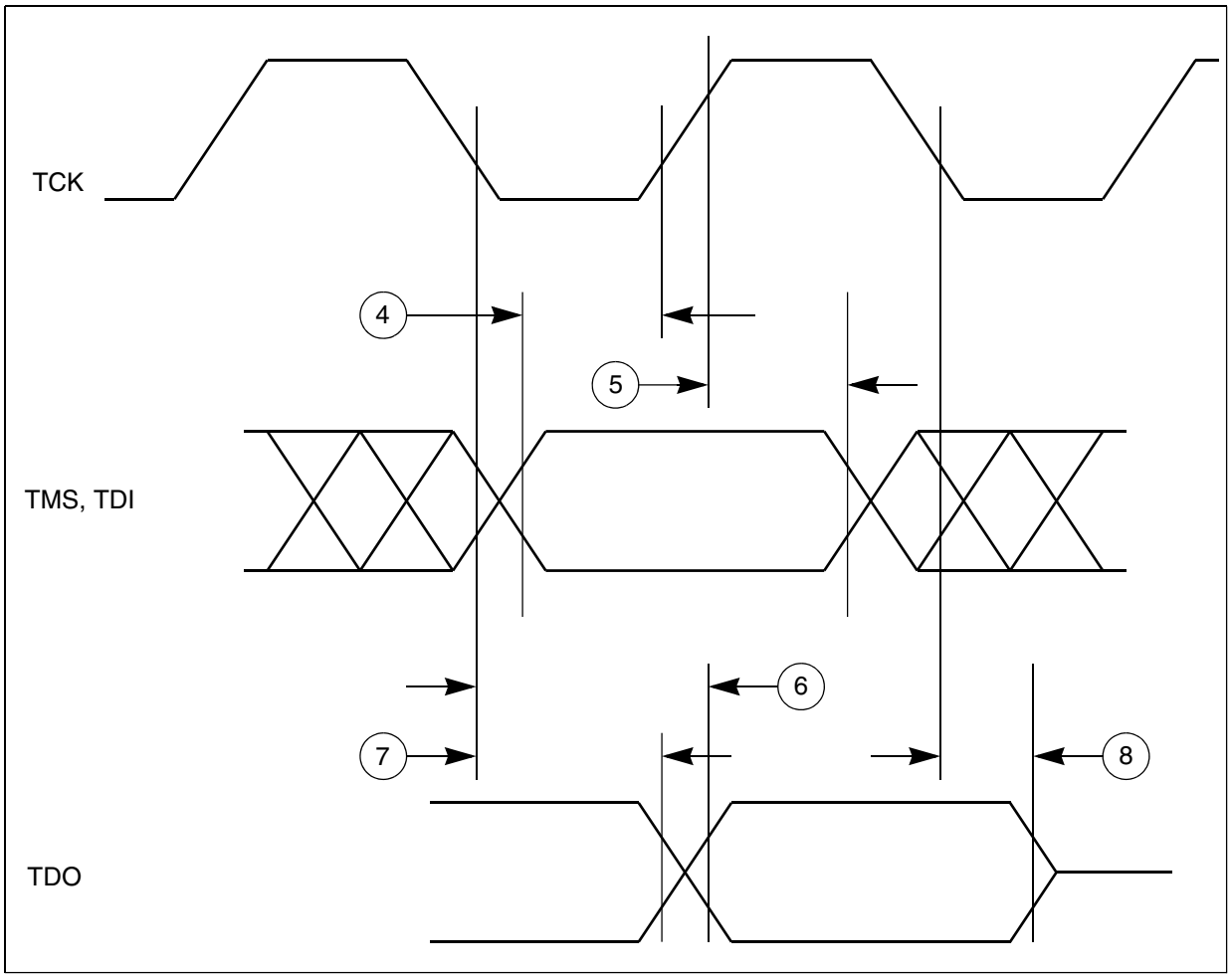

Figure 26. JTAG test access port timing

Table 46. Nexus debug port timing [1] (continued)

No.	Symbol	Parameter	Conditions	Min	Max	Unit
9	t_{NTDIH}, t_{NTMSH}	TDI, TMS Data Hold Time	—	5	—	ns
10	t_{JOV}	TCK Low to TDO/RDY Data Valid	—	0	25	ns

1. JTAG specifications in this table apply when used for debug functionality. All Nexus timing relative to MCKO is measured from 50% of MCKO and 50% of the respective signal.
2. For all Nexus modes except DDR mode, MDO, $\overline{\text{MSEO}}$, and $\overline{\text{EVTO}}$ data is held valid until next MCKO low cycle.
3. The system clock frequency needs to be four times faster than the TCK frequency.

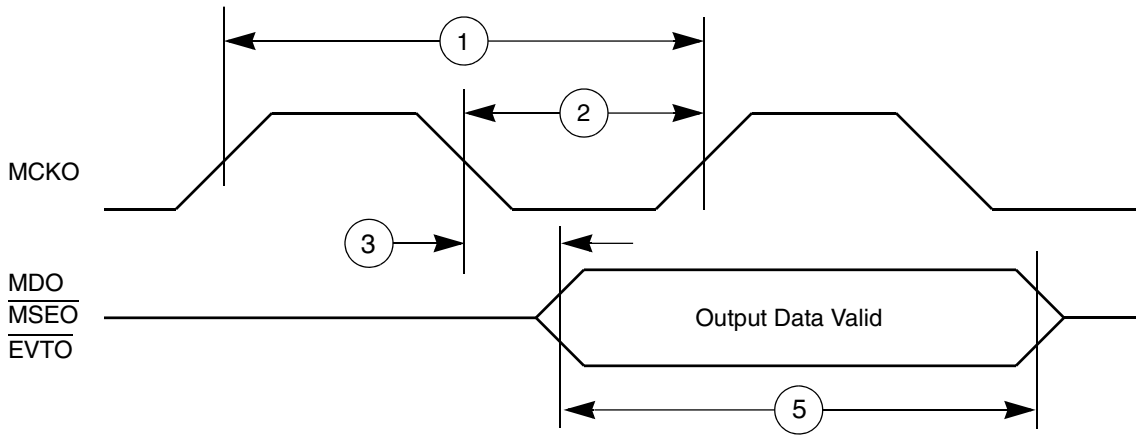

Figure 28. Nexus output timing

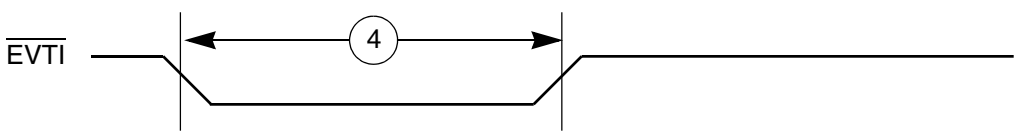

Figure 29. Nexus EVTI Input Pulse Width

Thermal attributes

Board type	Symbol	Description	256 MAPBGA	Unit	Notes
—	$R_{\theta JC}$	Thermal resistance, junction to case	7.9	°C/W	55
—	Ψ_{JT}	Thermal characterization parameter, junction to package top outside center (natural convection)	0.2	°C/W	66
—	$R_{\theta JB\_CSB}$	Thermal characterization parameter, junction to package bottom outside center (natural convection)	9.0	°C/W	77

1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
2. Per SEMI G38-87 and JEDEC JESD51-2 with the single layer board horizontal.
3. Per JEDEC JESD51-6 with the board horizontal
4. Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.
5. Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).
6. Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.
7. Thermal characterization parameter indicating the temperature difference between package bottom center and the junction temperature per JEDEC JESD51-12. When Greek letters are not available, the thermal characterization parameter is written as Psi-JB.

Board type	Symbol	Description	100 MAPBGA	Unit	Notes
Single-layer (1s)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	50.9	°C/W	1, 21,2
Four-layer (2s2p)	$R_{\theta JA}$	Thermal resistance, junction to ambient (natural convection)	27.0	°C/W	1,2,33
Single-layer (1s)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./ min. air speed)	38.0	°C/W	1,3
Four-layer (2s2p)	$R_{\theta JMA}$	Thermal resistance, junction to ambient (200 ft./ min. air speed)	22.2	°C/W	1,3

Table continues on the next page...

Board type	Symbol	Description	100 MAPBGA	Unit	Notes
—	$R_{\theta JB}$	Thermal resistance, junction to board	10.8	°C/W	44
—	$R_{\theta JC}$	Thermal resistance, junction to case	8.2	°C/W	55
—	Ψ_{JT}	Thermal characterization parameter, junction to package top outside center (natural convection)	0.2	°C/W	66
—	Ψ_{JB}	Thermal characterization parameter, junction to package bottom outside center (natural convection)	7.8	°C/W	77

1. Junction temperature is a function of die size, on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
2. Per SEMI G38-87 and JEDEC JESD51-2 with the single layer board horizontal.
3. Per JEDEC JESD51-6 with the board horizontal
4. Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.
5. Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).
6. Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. When Greek letters are not available, the thermal characterization parameter is written as Psi-JT.
7. Thermal characterization parameter indicating the temperature difference between package bottom center and the junction temperature per JEDEC JESD51-12. When Greek letters are not available, the thermal characterization parameter is written as Psi-JB.

8 Dimensions

8.1 Obtaining package dimensions

Package dimensions are provided in package drawing.

To find a package drawing, go to www.nxp.com and perform a keyword search for the drawing's document number:

Package	NXP Document Number
100 MAPBGA	98ASA00802D

Table continues on the next page...

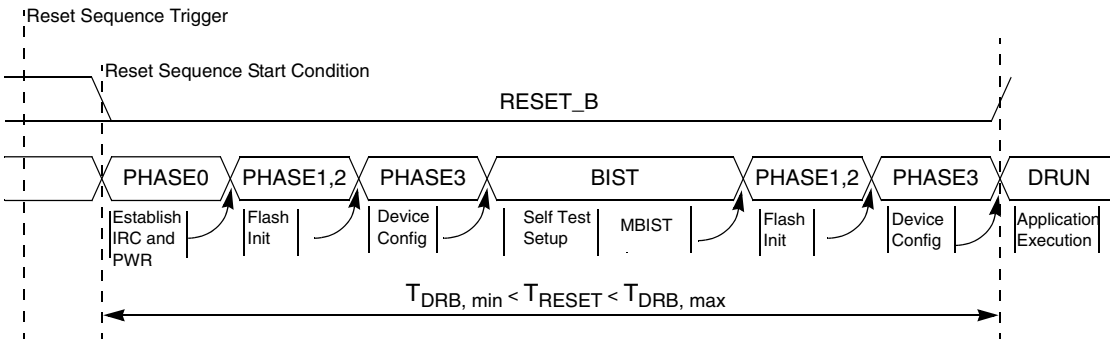

Figure 32. Destructive reset sequence, BIST enabled

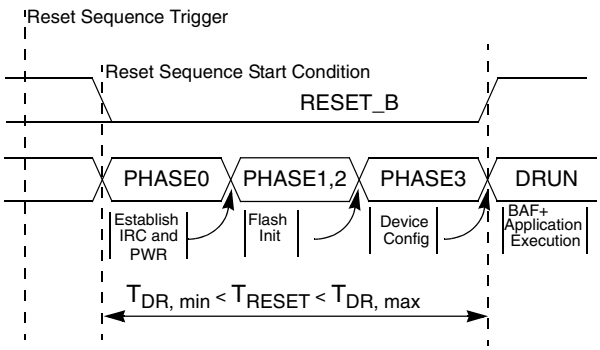

Figure 33. Destructive reset sequence, BIST disabled

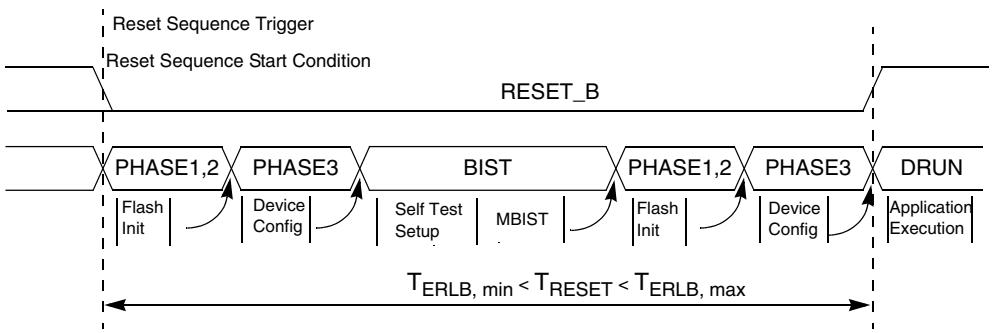

Figure 34. External reset sequence long, BIST enabled

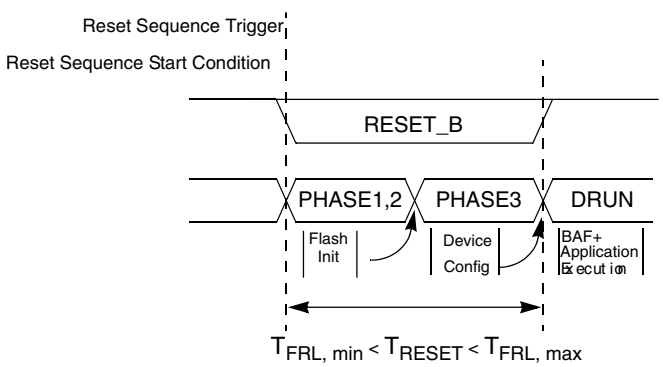

Figure 35. Functional reset sequence long

Table 51. Revision History (continued)

Rev. No.	Date	Substantial Changes

		• In section: Reset pad electrical characteristics
		  • Revised table, Reset electrical characteristics
		  • Deleted note, There are some specific ports that supports TTL functionality. These ports are, PB[4], PB[5], PB[6], PB[7], PB[8], PB[9], PD[0], PD[1], PD[2], PD[3], PD[4], PD[5], PD[6], PD[7], PD[8], PD[9], PD[10], and PD[11].
		• In section: PORST electrical specifications
		  • In table: PORST electrical specifications
		  • Updated 'Min' value for $W_{NFPORST}$
		• In section: Peripheral operating requirements and behaviours
		  • Changed section title from Input impedance and ADC accuracy to Input equivalent circuit and ADC conversion characteristics.
		  • Revised table: ADC conversion characteristics (for 12-bit) and ADC conversion characteristics (for 10-bit)
		  • Removed table, ADC supply configurations.
		• In section: Analogue Comparator (CMP) electrical specifications
		  • In table: Comparator and 6-bit DAC electrical specifications
		  • Updated 'Max' value of I_{DDLS}
		  • Updated 'Min' and 'Max' for V_{AIO} and DNL
		  • Updated 'Descripton' 'Min' 'Max' od V_H
		  • Updated row for t_{DHS}
		  • Added row for t_{DLS}
		  • Removed row for V_{CMPOh} and V_{CMPOl}
		• In section: Clocks and PLL interfaces modules
		  • In table: Main oscillator electrical characteristics
		  • V_{XOSCHS}: Removed values for 4 MHz.
		  • $T_{XOSCHSSU}$: Updated range to 8-40 MHz.
		  • In table: 16 MHz RC Oscillator electrical specifications
		  • Updated 'Max' for $T_{startup}$ and T_{LTJIT}
		  • Removed $F_{Untrimmed}$ row
		  • In table: 128 KHz Internal RC oscillator electrical specifications
		  • Fosc: Removed Uncaliberated 'Condition' and updated 'Min', 'Typ', and 'Max' for Caliberated condition
		  • Fosc: Updated 'Temperature dependence' and 'Supply dependence' Max values
		  • In table: PLL electrical specifications
		  • Removed entries for Input Clock Low Level, Input Clock High Level, Power consumption, Regulator Maximum Output Current, Analog Supply, Digital Supply (V_{DD_LV}), Modulation Depth (Down Spread), PLL reset assertion time, and Power Consumption
		  • Removed 'Typ' value for Duty Cycle at pllclkout
		  • Removed 'Min' value for Lock Time in calibration mode.
		  • In table: Jitter calculation
		  • Added 1 Sigma Random Jitter and Total Period Jitter values for Long Term Jitter (Interger and Fractional Mode) rows.

		• In section Flash read wait state and address pipeline control settings • In Flash Read Wait State and Address Pipeline Control: Updated APC for 40 MHz. • Removed section: On-chip peripherals

Table continues on the next page...

Table 51. Revision History (continued)

Rev. No.	Date	Substantial Changes
Rev 5.1	22 May 2017	• Removed the Introduction section from Section 4 "General". • In AC Specifications@3.3V section, removed note related to Cz results and added two notes. • In AC Specifications@5V section, added two notes. • In ADC Electrical Specifications section, added spec value of "ADC Analog Pad" at Max leakage (standard channel)@ 105 C T_A in "ADC conversion characteristics (for 10-bit)" table. • In PLL Electrical Specifications section, updated the first footnote of "Jitter calculation" table. • In Analog Comparator Electrical Specifications section, updated the TDLS (propagation delay, low power mode) max value in "Comparator and 6-bit DAC electrical specifications" table to 21 us. • In Recommended Operating Conditions section, updated the footnote link to T_A in "Recommended operating conditions (V DD_HV_x = 5V)" table.

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